



11th MiNaPAD

Micro/Nano-Electronics Packaging & Assembly, Design and Manufacturing Forum

June 19-20, 2024 – Grenoble, France



Call for extended abstracts

Extended Abstracts (2 pages typical, including graphs, pictures, ...) are requested on the following topics :

Advanced packaging :
TSVs, 2.5 & 3D integration, heterogeneous integration, wafer level packaging, embedded IC packages, SiP, PoP, MEMS packaging, advanced substrates, Hybrid bonding, Fan Out wafer and panel level processes, Chiplets integration

Packaging of power devices:
SiC, GaN, Si front end technologies,
Dicing of SiC wafers, wafer thinning, back side metallization and Taiko ring holder and removal, die attach by Ag sintering, thick Al or Cu wire bonding, overmolding of large modules, leadframe attach on ceramic

Assembly processes and technologies:
Bonding, advanced dicing, flux, cleaning, dispensing, coating, materials & equipment related to assembly manufacturing and business aspects of the industry.

Advanced interconnections:
Flip-chip including ultra-fine pitches approaches, interconnections, IMC studies, bumping techniques (solder bumps, Cu pillars,...) disruptive interconnections, optical connections.

Novel technologies and applications:
Flexible/stretchable packaging, nanomaterial for interconnections, green/bio and sustainable technologies for packaging, additive manufacturing, Nano manufacturing, printed electronics and wearable, paper-based PCB

Environmental-friendly materials and processes:
Lead-free and PFAS-free materials, lower temperature processing, water reclaiming & recycling”, bio-sourced materials

Materials equipment and processes:
3D materials, conductive & non-conductive adhesives, underfill, mold compound , disruptive solder alloys, thermal interface. Innovative equipment for assembly & packaging.

Quality and Reliability:
Applied reliability for LED, Displays, IoT, MEMS, memories, medical devices, chip-package and package-PCB interaction. Life models, failure analysis techniques & characterizations, metrology equipment and inspection methods

Imaging & photonics :
Assembly & packaging technologies for optical and photonics applications : imaging, displays, silicon photonics, optical sensors, high energy physics and medical imaging.

Thermal/mechanical simulation and characterization:
Components, boards & system level modelling for : interconnections, interposers, substrates, WLP & embedded packages, power modules, optical packaging, RF and MEMS.

Practical information

Organization :

IMAPS France

Email: imaps.france@orange.fr

Web: www.france.imapseurope.org

General chair: Jean-Marc YANNOU (ASE Europe)

Technical Chairs:

Sanae BOULAY (NXP),

Jean-Luc DIOT (Assemblinno),

Romain COFFY (ST Microelectronics),

Valérie VOLANT (ST Microelectronics),

Jean-Charles SOURIAU (CEA-LETI),

Christophe ZINCK (ASE),

Laurent MENDIZABAL (CEA-LETI),

Alexandre VAL (VALEO).



Location : Close to Grenoble Railway Station

WTC / Congress center

5 -7 , place Robert Schuman – BP 1521

38025 Grenoble Cedex 1

FRANCE



Exhibition area :

Equipment & Product suppliers in the WTC Atrium during the workshop.

Important dates

Extended abstracts submission date :

March 20th, 2024

Your submission must include the mailing address, business phone number and email address and the content must be without commercial information.

Address your abstract to :

imaps.france@orange.fr

Notification of acceptance :

Authors will be notified of paper acceptance with instructions for presentation **before April 8th, 2024.**

Presentations :

Presentation should be ready one day before the workshop and supply to the chairwomen or chairmen of your session.

Social event :

Evening dinner & visit on the 19th of June 2024



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